

**POLY(PHENYLENE ETHER)-POLYVINYL THERMOSETTING ADHESIVES,
FILMS, AND SUBSTRATES MADE THEREFROM**

ABSTRACT OF THE DISCLOSURE

This invention is directed to an adhesive resin composition having better processability, exhibiting reduced B-staged (partially cured) friability, and capable of being produced in a wide range of flow characteristics dependent upon the applications desired. Specifically, the composition, comprising a poly(arylene ether)-polyvinyl resin and curable unsaturated monomer, is applied to a metal foil or thermoplastic substrate or a free-standing film. The thermoplastic substrate may have an electrically conductive metal, such as copper, on one side. Better final film properties can be achieved by tailored functionality of cross-linking by control of ingredients and/or chain length (molecular weight) of ingredients used in making the novel adhesive composition.